APPLICATION DATA SHEET

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[FLIP-CHIP PACKAGE SUBSTRATE]

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Inventor Information:

Inventor 1:

Applicant Authority Type: Inventor Citizenship: TW
Name prefix: Mr.

Given Name: Chi-Hsing

Family Name: Hsu

Residence:

City of Residence: Taipei Hsien

Country of Residence: TW

Address-1 of Mailing Address: c/o 8F, No. 533, Chung-Cheng Rd., Hsintien

Address-2 of Mailing Address:

City of Mailing Address: Taipei Hsien

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address: TW

Phone: Fax:

E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561

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